

LASER PROCESSING APPARATUS

ABSTRACT OF THE DISCLOSURE

A laser processing apparatus includes a chuck table configured to hold a workpiece, a laser beam irradiating unit having a condenser configured to condense and apply a laser beam to the workpiece held on the chuck table, a moving unit configured to move the chuck table and a condensing point of the laser beam relative to each other, a measuring unit configured to measure a beam profile of the laser beam; and a control unit configured to control each constituent element. The measuring unit is disposed adjacent to the chuck table so as to have a light receiving surface parallel with a holding surface of the chuck table.

[Fig. 2]